



February 20, 2013

Microsemi SoC RoHS Certificate of Compliance

Microsemi SoC part numbers represented by the “**G**” nomenclature inserted after the package designator indicates that the device is RoHS 6 compliant. These part numbers are in compliance with Directive 2011/65/EU of the European Parliament and the Council of 8 June 2011 on the restrictions of the use of certain hazardous substances, in electrical and electronic equipment (Recast).

Example: RoHS 6 compliant part number: A40MX04-PL**G**44.

Note: Prior to May 2005, the nomenclature for Lead-Free part numbers was an “**X79**” designator at the end of a part number, i.e. A40MX04-PL44**X79**, which has been replaced by the “**G**” nomenclature.

RoHS 6 compliant devices (with a “**G**”) do not include the following RoHS banned substances:

1. Lead and lead compounds
2. Mercury and mercury compounds
3. Cadmium and Cadmium compounds
4. Hexavalent Chromium and Hexavalent Chromium compounds
5. PBB (polybromobiphenyl)
6. PBDE (polybrominated diphenyl ethers)

Microsemi SoC’s standard devices without the “**G**” designators are RoHS compliant and uses exemption 7(a) Lead in high melting temperature type solders. (Example part number: A40MX04-PL44)

For RoHS compliant plastic quad flat packages (PQFP, TQFP, and VQFP), Microsemi SoC uses 10um thick, pure tin matte plating. There is a risk in using pure tin in that tin whiskers may form after a period of time. Microsemi SoC currently has no plans to offer hermetic packages with 100% pure tin, and will continue to offer plastic packages, ceramic packages, and Mil-Std/QML devices with traditional lead solder as well as RoHS compliant packages.

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